

Appl. No. 10/620,127  
Response dated November 9, 2004  
Reply to Office Action of October 20, 2004

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listing, of claims in the application:

**Listing of Claims:**

What is claimed is:

Claim 1 (currently amended): An air bridge produced by:

depositing one or more circuit components on a substrate;

depositing a sacrificial material over at least a portion of the circuit components;

depositing a crossover circuit trace of uniform composition over the sacrificial material, the crossover circuit trace crossing over the circuit components; and thermally decomposing the sacrificial material.

Claim 2 (withdrawn): The air bridge of claim 1, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

Claim 3 (original): The air bridge of claim 1, wherein the sacrificial material comprises polynorbomene.

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Claim 4 (original): The air bridge of claim 1, wherein the one or more circuit components comprise a circuit trace.

Claim 5 (original): The air bridge of claim 4, wherein the circuit trace comprises a signal trace.

Claim 6 (original): The air bridge of claim 4, wherein the circuit trace comprises a ground trace.

Claim 7 (original): The air bridge of claim 4, wherein the circuit trace comprises a power trace.

Claim 8 (original): The air bridge of claim 1, wherein the crossover circuit trace comprises a signal trace.

Claims 9 – 20 (canceled)

Claim 21 (currently amended): An air bridge produced by:  
    depositing one or more circuit components on a substrate;  
    depositing a sacrificial material over at least a portion of the circuit components;

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depositing a crossover circuit trace of uniform composition over the sacrificial material, the crossover circuit trace crossing over the circuit components and being directly supported by the substrate on opposite sides of the sacrificial material; and thermally decomposing the sacrificial material.

Claim 22 (withdrawn): The air bridge of claim 21, wherein depositing a sacrificial material comprises depositing the sacrificial material in a manner causing the sacrificial material to be dome shaped.

Claim 23 (previously presented): The air bridge of claim 21, wherein the sacrificial material comprises polynorbornene.

Claim 24 (previously presented): The air bridge of claim 21, wherein the one or more circuit components comprise a circuit trace.

Claim 25 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a signal trace.

Claim 26 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a ground trace.

Claim 27 (previously presented): The air bridge of claim 24, wherein the circuit trace comprises a power trace.

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Claim 28 (previously presented): The air bridge of claim 21, wherein the crossover circuit trace comprises a signal trace.